

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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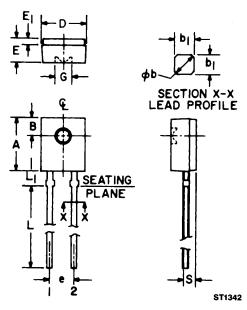






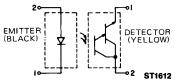
H23B1

PACKAGE DIMENSIONS



SYMBOL	MILLIMETERS		INC	NOTES	
CHINDOL	MIN.	MAX.	MIN.	MAX.	NOILS
A	5.59	5.80	.220	.228	
В	1.78	NOM.	.070	NOM.	2
® b	.60	.75	.024	.030	1
b ₁	.51	NOM.	.020	NOM.	1
D	4.45	4.70	.175	.185	
E	2.41	2.67	.095	.105	
Ε,	.58	.69	.023	.027	
е	2.41	2.67	.095	.105	3
G	1.98	NOM.	.078	NOM.	
L	12.7		.500	-	
L,	1.40	1.65	.055	.065	
S	.83	.94	.033	.037	3

PACKAGE OUTLINE



NOTES

- TWO LEADS. LEAD CROSS SECTION DIMENSIONS UNCONTROLLED WITHIN 1.27 mm (0.50") OF SEATING PLANE.
- 2. CENTERLINE OF ACTIVE ELEMENT LOCATED WITHIN .25 mm (.010") OF TRUE POSITION.
- 3. AS MEASURED AT THE SEATING PLANE.
- 4. INCH DIMENSIONS DERIVED FROM MILLIMETERS.

DESCRIPTION

The H23B1 is a matched emitter-detector pair which consists of a gallium arsenide infrared emitting diode and a silicon photodarlington. The clear epoxy packaging system is designed to optimize the mechanical resolution, coupling efficiency, cost, and reliability. The devices are marked with a color dot for easy identification of the emitter and detector.

FEATURES

- Good optical to mechanical alignment
- Color dot for easy recognition of LED and phototransistor
- Low cost

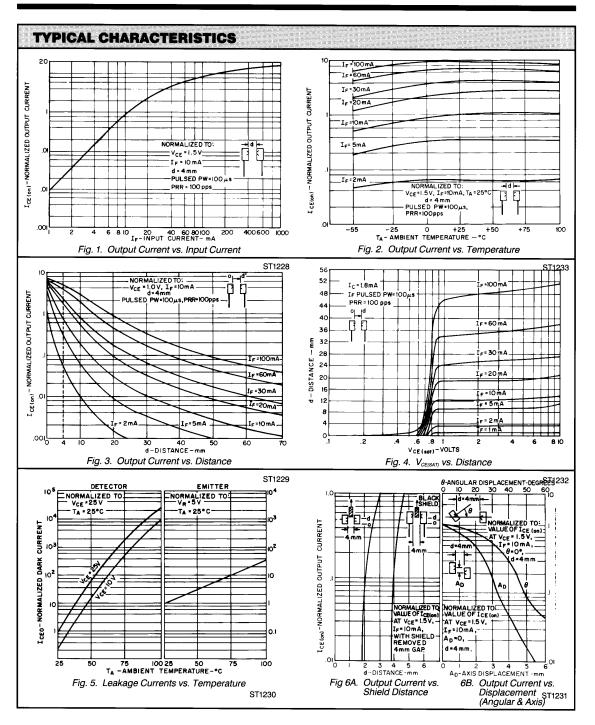


ABSOLUTE MAXIMUM RATINGS (T _A = 25°C Unless Ot	herwise Specified)
Storage Temperature Operating Temperature Soldering:	-55°C to +100°C -55°C to +100°C
Lead Temperature (Iron)	
INPUT DIODE Continuous Forward Current Reverse Voltage Power Dissipation	6.0 Volts
OUTPUT DARLINGTON Collector-Emitter Voltage Emitter-Collector Voltage Power Dissipation	

ELECTRICAL CHARACTERISTICS (T _A = 25°C Unless Otherwise Specified)							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	TEST CONDITIONS	
INPUT DIODE							
Forward Voltage	$V_{\scriptscriptstyle F}$	_		1.7	٧	$I_F = 60 \text{ mA}$	
Reverse Leakage Current	I _R	_		1.0	μA	$V_R = 3V$	
Reverse Breakdown Voltage	V _R	6.0			V	$I_R = 10 \mu A$	
OUTPUT DARLINGTON	176						
Emitter-Collector Breakdown	BV_{eco}	7.0		_	٧	$I_{\rm E} = 100 \mu A, Ee = 0$	
Collector-Emitter Breakdown	BV _{CEO}	30		_	V	I _c = 1 mA, Ee=0	
Collector-Emitter Leakage	I _{CEO}	_		100	nA	V _{CE} = 25 V, Ee=0	
COUPLED	-			-			
On-State Collector Current	I _{C(ON)}	7.5		_	mA	$I_F = 10 \text{ mA}, V_{CE} = 1.5 \text{ V}^{(6)}$	
Saturation Voltage	V _{CE(SAT)}			1.0	٧	$I_F = 10 \text{ mA}, I_C = 1.8 \text{ mA}^{(6)}$	
Turn-On Time	t _{on}		8	_	μS	$I_F = 30 \text{ mA}, V_{cc} = 5 \text{ V}, R_L = 2.5 \text{K}$	
Turn-Off Time	t _{off}		50		μS	$I_F = 30 \text{ mA}, V_{CC} = 5 \text{ V}, R_I = 2.5 \text{ Kg}$	

NOTES

- Derate power dissipation linearly 1.33mW/°C above 25°C.
 Derate power dissipation linearly 2.00mW/°C above 25°C.
 RMA flux is recommended.
- 4. Methanol or Isopropyl alcohols are recommended as cleaning agents.
- 5. Soldering iron tip 1/6" (1.6 mm) minimum from housing.
 6. Coupled characteristics are measured at a separation distance of .155" (4 mm) with the lenses of the emitter and detector on a common axis within 0.1mm and parallel within 5°.





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